



P/N 1110748 Surface Mount-to-DIP JEDEC SOT-25, SOT-23A-6 Adapter

FEATURES

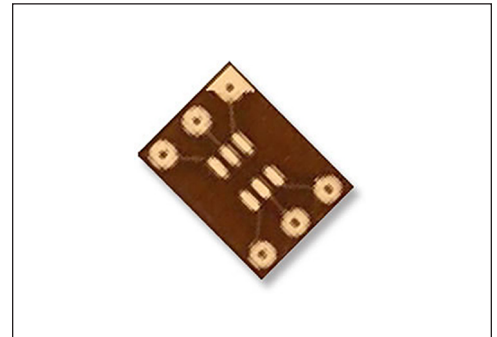
- Allows for breadboarding or substitution of Microgate SOT-23A-6 and SOT-25 IC and transistor packages into 0.100 [2.54] pitch proto boards or PC boards.
- Solder masked top-side pads allow user to hand solder devices directly to topside of adapter with fewer problems of solder bridging.
- Longer male bottom Pins available at special request for easy use of probe clips.
- Large topside pads allow for soldering test pins, jumpers, etc. to top of adapter.

GENERAL SPECIFICATIONS

- BOARD MATERIAL: 0.062 [1.58] thick FR-4 manufactured to IPC-600E, Class 2 standards, with 1-oz. Cu traces, both sides
- PADS: HASL
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: 200 μ [5.08 μ] Sn/Pb 93/7 ASTM B579-73 over 100 μ [2.54 μ] Ni per SAE-AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS

- SUGGESTED PCB HOLE SIZE: 0.028 \pm 0.003 [0.71 \pm 0.08] dia.



CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION

P/N 1110748

P/N 1110748-P for Panelized Version

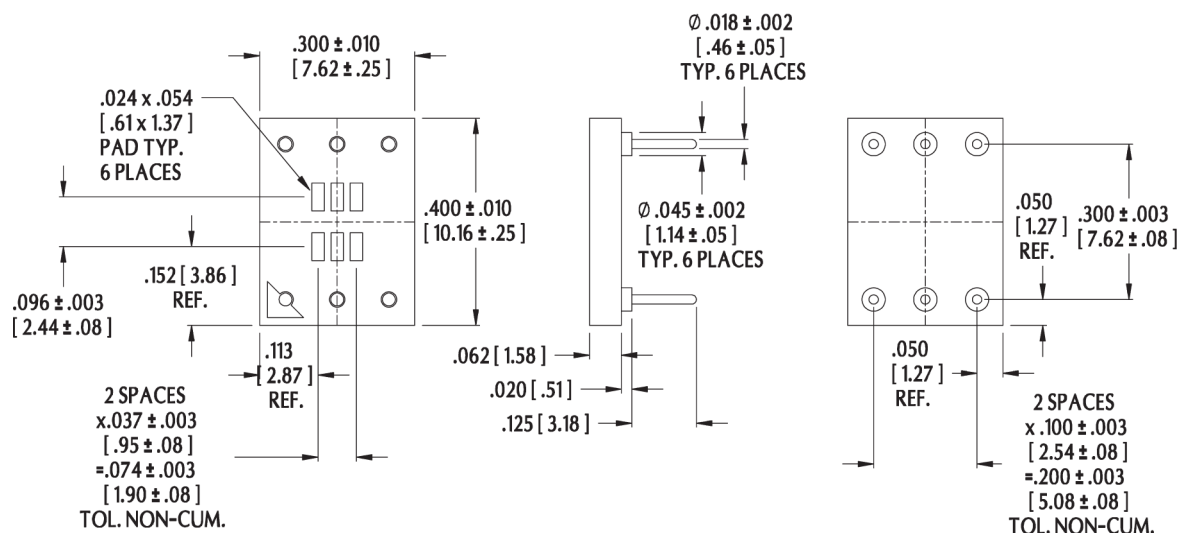
ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: \pm 0.005 [0.13] UNLESS OTHERWISE SPECIFIED

ALL CAC'S ARE MANUFACTURED AND INSPECTED USING IPC -610B CLASS 2 GUIDELINES

CONSULT FACTORY FOR MOUNTING CONSIDERATIONS OF CONSIGNED CHIPS.

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS



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